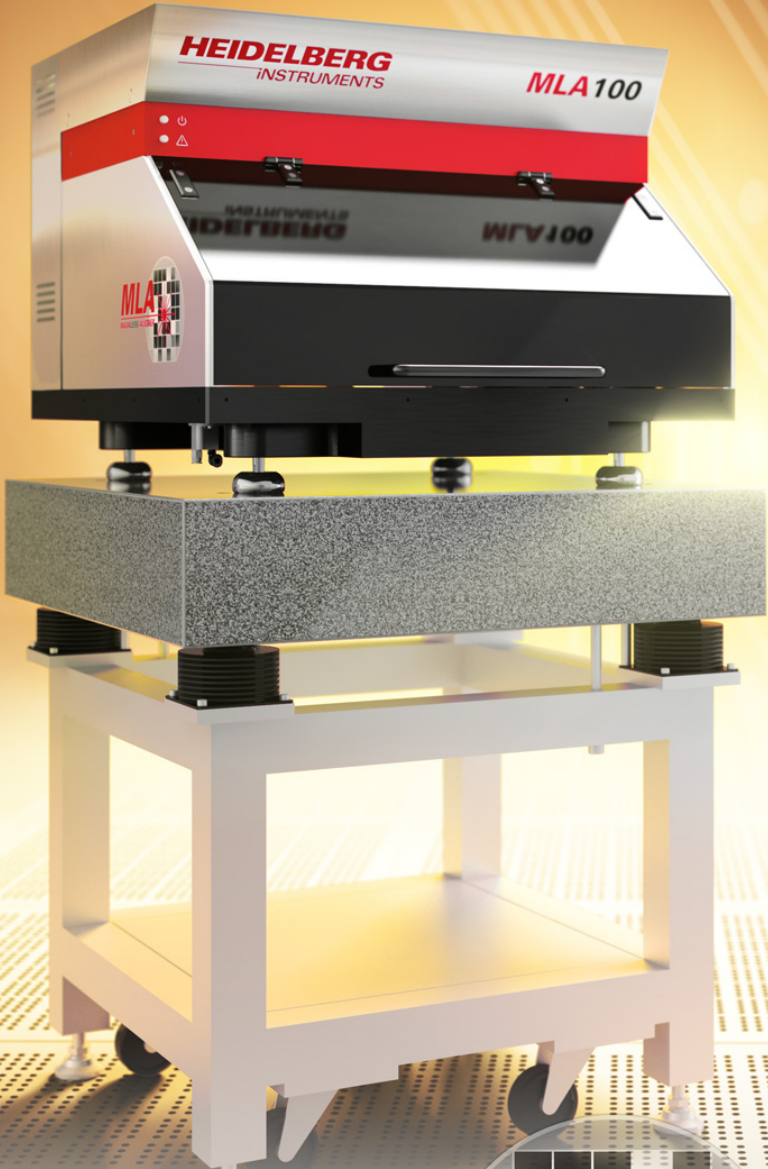


**MLA100**

**HEIDELBERG**  
INSTRUMENTS



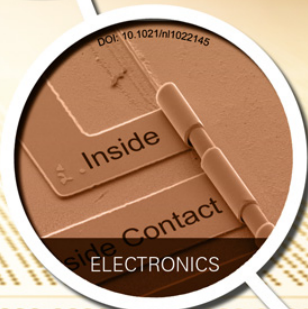
MEMS



SENSORS



GRAY SCALE



ELECTRONICS

**MLA**  
MASKLESS ALIGNER



**GO MASKLESS**  
**ACHIEVE MORE**



#### STEP 1: SYSTEM SETUP

- Intuitive User Interface
- Support for all standard input formats (dxf, gdsii, cif, gerber)
- CAD Software for design creation included

**MLA100**

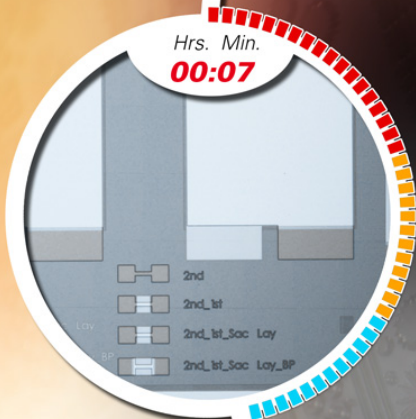


MORE INFO? SCAN THIS!



#### STEP 2: LOADING

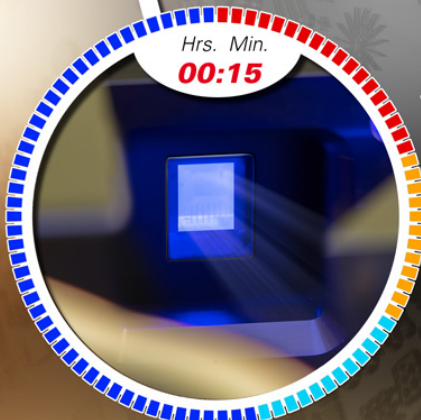
- Simple loading procedure
- One chuck for all substrates from 5 x 5 mm<sup>2</sup> to 100 x 100 mm<sup>2</sup>
- Automatic substrate size detection
- No need for edge-bead removal or wedge compensation



#### STEP 3: ALIGNMENT

- High precision topside alignment
- Fast alignment procedure
- Simple alignment on thick resists and small substrates
- Alignment accuracy  $\leq 1 \mu\text{m}$

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MASKLESS ALIGNER



#### STEP 4: EXPOSURE

- Min. feature size of 1  $\mu\text{m}$
- Exposure time for 20 x 20 mm<sup>2</sup> approx. 8 min
- Non-contact exposure
- High Aspect ratio exposures in thick resists
- Basic gray scale exposure mode
- Compatible to g-,h- and i-line resists



**GO MASKLESS** \_\_\_\_\_  
\_\_\_\_\_ **ACHIEVE MORE**